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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: **SUNOHARA, Masahiro, et al.**

Group Art Unit: **2826**

Serial No.: **10/756,763**

Examiner: **Alexander O. WILLIAM**

Filed: **January 14, 2004**

**P.T.O. Confirmation No.: 1523**

**FOR: AN ELECTRONIC PARTS PACKAGING STRUCTURE IN WHICH A SEMICONDUCTOR CHIP IS MOUNTED ON A WIRING SUBSTRATE AND BURIED IN AN INSULATION FILM (As Amended)**

**AMENDMENT UNDER 37 CFR §1.111**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

February 24, 2006

Sir:

In response to the Office Action dated **December 16, 2005**, please amend the above-identified application as follows:

**Amendments to the Title** are reflected on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 10 of this paper.

**AMENDMENTS TO THE TITLE:**

The title of the present invention has been changed to read as follows:

--An Electronic Parts Packaging Structure in which a Semiconductor Chip is mounted on a  
Wiring Substrate and buried in an Insulation Film--